

<b>STN</b>	<b>Dosky s plošnými spojmi a zostavy dosiek s plošnými spojmi</b> <b>Konštrukcia a používanie</b> <b>Časť 6-4: Základné požiadavky na rozmerové výkresy súčiastok na povrchovú montáž (SMD) z pohľadu návrhu plošných spojov</b>	<b>STN</b> <b>EN IEC 61188-6-4</b>  34 6512
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Printed boards and printed board assemblies - Design and use - Part 6-4: Land pattern design - Generic requirements for dimensional drawings of surface mounted components (SMD) from the viewpoint of land pattern design

Táto norma obsahuje anglickú verziu európskej normy.  
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 11/19

Obsahuje: EN IEC 61188-6-4:2019, IEC 61188-6-4:2019

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EUROPEAN STANDARD

**EN 61188-6-4**

NORME EUROPÉENNE

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July 2019

ICS 31.180

English Version

Printed boards and printed board assemblies - Design and use -  
Part 6-4: Land pattern design - Generic requirements for  
dimensional drawings of surface mounted components (SMD)  
from the viewpoint of land pattern design  
(IEC 61188-6-4:2019)

Cartes imprimées et cartes imprimées équipées -  
Conception et utilisation - Partie 6-4: Conception de la zone  
de report - Exigences génériques pour les dessins  
dimensionnels de composants montés en surface (CMS) du  
point de vue de la conception de la zone de report  
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Leiterplatten und Flachbaugruppen - Konstruktion und  
Anwendung - Teil 6-4: Allgemeine Anforderungen an SMD-  
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**EN 61188-6-4:2019 (E)****European foreword**

The text of document 91/1561/FDIS, future edition 1 of IEC 61188-6-4, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 61188-6-4:2019.

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IEC 60191-1	NOTE	Harmonized as EN IEC 60191-1
IEC 60191-6	NOTE	Harmonized as EN 60191-6
IEC 60191-6-1	NOTE	Harmonized as EN 60191-6-1
IEC 61188-5-1	NOTE	Harmonized as EN 61188-5-1
IEC 61188-5-2	NOTE	Harmonized as EN 61188-5-2
IEC 61188-5-3	NOTE	Harmonized as EN 61188-5-3
IEC 61188-5-4	NOTE	Harmonized as EN 61188-5-4
IEC 61188-5-5	NOTE	Harmonized as EN 61188-5-5
IEC 61188-5-6	NOTE	Harmonized as EN 61188-5-6
IEC 61188-5-8	NOTE	Harmonized as EN 61188-5-8
IEC 61191-1	NOTE	Harmonized as EN IEC 61191-1
IEC 61191-2	NOTE	Harmonized as EN 61191-2

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NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: [www.cenelec.eu](http://www.cenelec.eu).

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60194	-	Terms and definitions for printed circuits	-	-
IEC 60194-2	-	Printed boards design, manufacture and assembly - Vocabulary - Part 2: Common usage in electronic technologies as well as printed board and electronic assembly technologies	-	-



IEC 61188-6-4

Edition 1.0 2019-05

# INTERNATIONAL STANDARD

## NORME INTERNATIONALE



**Printed boards and printed board assemblies – Design and use –  
Part 6-4: Land pattern design – Generic requirements for dimensional drawings  
of surface mounted components (SMD) from the viewpoint of land pattern  
design**

**Cartes imprimées et cartes imprimées équipées – Conception et utilisation –  
Partie 6-4: Conception de la zone de report – Exigences génériques pour les  
dessins dimensionnels de composants montés en surface (CMS) du point  
de vue de la conception de la zone de report**



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dessins dimensionnels de composants montés en surface (CMS) du point  
de vue de la conception de la zone de report**

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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

**PRINTED BOARDS AND PRINTED BOARD ASSEMBLIES –  
DESIGN AND USE –****Part 6-4: Land pattern design – Generic requirements for dimensional  
drawings of surface mounted components (SMD) from the viewpoint of  
land pattern design**

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FDIS	Report on voting
91/1561/FDIS	91/1572/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 61188 series, published under the general title *Printed boards and printed board assemblies – Design and use*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

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## **PRINTED BOARDS AND PRINTED BOARD ASSEMBLIES – DESIGN AND USE –**

### **Part 6-4: Land pattern design – Generic requirements for dimensional drawings of surface mounted components (SMD) from the viewpoint of land pattern design**

#### **1 Scope**

This part of IEC 61188 specifies generic requirements for dimensional drawings of SMD from the viewpoint of land pattern design.

The purpose of this document is to prevent land pattern design issues caused by lack of information and/or misuse of the information from SMD outline drawing as well as to improve the utilization of IEC 61188 series.

This document is applicable to the SMD of semiconductor devices and electrical components.

#### **2 Normative references**

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60194, *Printed board design, manufacture and assembly – Terms and definitions*

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